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Special Session on “Emerging Technologies-driven Cloud Manufacturing”

organized by

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Call for Papers

Theme:

Nowadays, emerging technologies such as the Internet of Things (IoT), Artificial Intelligence (AI), 5G, blockchain, robotics, edge computing, big data, and digital twin are undergoing rapid development, and have potentials to drive the further development of cloud manufacturing. Driven by and fusion with these emerging technologies, cloud manufacturing would evolve into a huge, intelligent manufacturing system characterized by open architecture, intelligent services, intelligent data analysis and knowledge mining, intelligent operations, precise edge control, and product lifecycle intelligent applications, etc. How to effectively incorporate these emerging technologies into and achieve seamless integration with cloud manufacturing is an important and challenging problem worthy of study. Therefore, this Special Session focuses on emerging technologies-driven cloud manufacturing to explore new development opportunities with emerging technologies and push forward its further development.

Topics of interest include, but are not limited to:

Blockchain-based open architecture and security mechanisms; intelligent big data analysis; digital twins; intelligent manufacturing services; intelligent service search, matching, composition, and scheduling; cloud-based resource/capability sharing; Intelligent machines and robots; edge computing and edge manufacturing; mobile Internet-based applications; intelligent knowledge mining; deep learning and deep reinforcement learning for manufacturing; cloud-based cyber-physical production systems; cloud-based 3D printing, virtual reality (VR)/Augmented reality (AR); 5G.

Submissions Procedure: All the instructions for paper submission are included in the conference website <https://indin2020.medmeeting.org/en>

Fast track to transactions: INDIN 2020 presents a unique chance of fast-tracking best papers to IEEE Transactions on Industrial Informatics (TII). Authors intended to use the fast track shall submit papers in the form following the transactions requirements: length up to 8 pages, double-column IEEE format, without authors' names and affiliations. If the paper is accepted and recommended for the transactions' submission, the authors will be asked to:

- 1) Revise the paper according to the reviewers' comments and submit it to the TII with attached point by point summary of revisions. The paper will be then subject to double blind review process of TII.
- 2) Prepare a shortened, 4 page long version for the INDIN proceedings and submit it by the 'final manuscripts due' deadline of INDIN 2020. This version shall include authors names and affiliations as per the usual INDIN template.

Deadlines:

Deadline for submission of papers:	March 07, 2020
Notification of acceptance of papers:	April 18, 2020
Final manuscripts due:	May 09, 2020